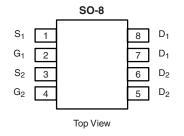


Vishay Siliconix

Dual N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)		
60	0.058 at V _{GS} = 10 V	5.3	13 nC		
60	0.072 at V _{GS} = 4.5 V	4.7	13110		



FEATURES

G1 C

Halogen-free According to IEC 61249-2-21
Available

G₂ **C**

 D_2

S₂

N-Channel MOSFET

• TrenchFET[®] Power MOSFET

APPLICATIONS

LCD TV CCFL Inverter

Dı

S₁

N-Channel MOSFET



HALOGEN FREE Available

Ordering Information: Si4900DY-T1-E3 (Lead (Pb)-free) Si4900DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATING	S T _A = 25 °C, unle	ss otherwise r	noted		
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		5.3		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C	I _D	4.3		
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	T _A = 25 °C		4.3 ^{b, c}		
	T _A = 70 °C		3.4 ^{b, c}	•	
Pulsed Drain Current (10 µs Width)		I _{DM}	20	A	
	T _C = 25 °C		2.6		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.7 ^{b, c}		
Avalanche Current		I _{AS}	11		
Single-Pulse Avalanche Energy	L = 0 1 mH	E _{AS}	6.1	mJ	
	T _C = 25 °C	-	3.1		
Maximum Power Dissipation	T _C = 70 °C		2		
	T _A = 25 °C	P _D	2 ^{b, c}	W	
	T _A = 70 °C	1	1.3 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, d}		R _{thJA}	55	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	33	40	0/10	

Notes:

a. Based on $T_C = 25$ °C.

b. Surface Mounted on 1" x 1" FR4 board.

c. t = 10 s.

d. Maximum under Steady State conditions is 110 °C/W.

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Parameter	Symbol	erwise noted Test Conditions	Min.	Тур.	Max.	Unit	
Static					-		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 050 A		55		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6			
		$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1		3		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 5 \text{ mA}$		2.5		V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = 20 V$			100	nA	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α	
	_	V _{GS} = 10 V, I _D = 4.3 A		0.046	0.058	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 3.9 \text{ A}$		0.059	0.072		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 4.3 A		15		S	
Dynamic ^b		-			I		
Input Capacitance	C _{iss}			665		pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		75			
Reverse Transfer Capacitance	C _{rss}			40			
		$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4.3 \text{ A}$		13	20	nC	
Total Gate Charge	Qg	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 4.3 \text{ A}$		6	9		
Gate-Source Charge	Q _{gs}			2.3			
Gate-Drain Charge	Q _{gd}			2.6			
Gate Resistance	R _g	f = 1 MHz		2		Ω	
Turn-On Delay Time	t _{d(on)}			15	25		
Rise Time	t _r	V_{DD} = 30 V, R _I = 8.8 Ω		65	100	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 3.4 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		15	25		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			10	15	ns	
Rise Time	t _r	V_{DD} = 30 V, R _I = 8.8 Ω		15	25	1	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 3.4 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		20	30	-	
Fall Time	t _f			10	15	-	
Drain-Source Body Diode Characterist	tics				I		
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			2.6		
Pulse Diode Forward Current	I _{SM}				20	A	
Body Diode Voltage	V _{SD}	I _S = 1.7 A, V _{GS} = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			30	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			32	50	nC	
Reverse Recovery Fall Time t _a		$I_F = 1.7 \text{ A}, \text{ dl/dt} = 100 \text{ A/}\mu\text{s}, \text{ T}_J = 25 ^\circ\text{C}$		25		1	
Reverse Recovery Rise Time	t _b	1		5		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Si4900DY

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T_C = 125 °C

2.5

3.0

3.5

25 C

2.0

Ciss

40

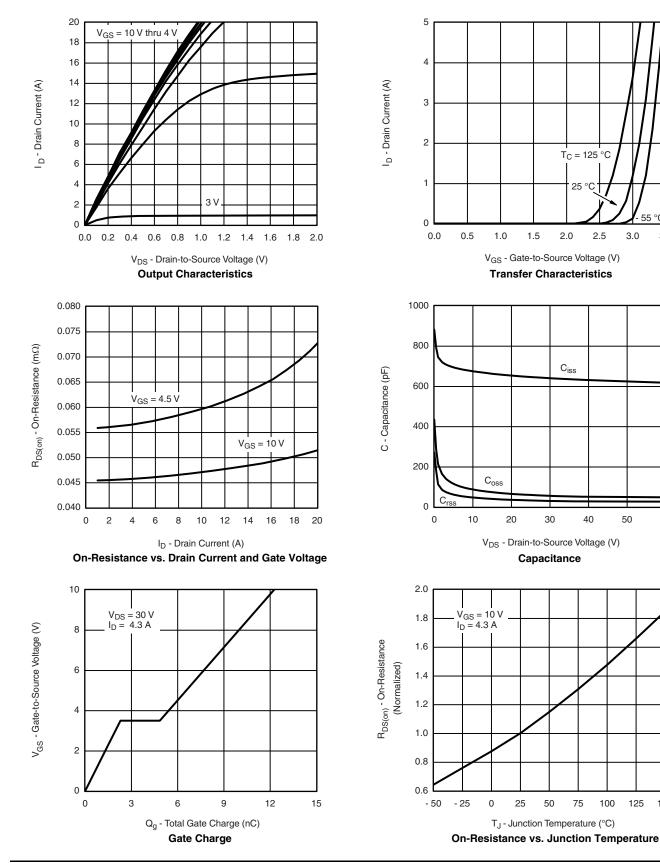
75

100

50

60

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



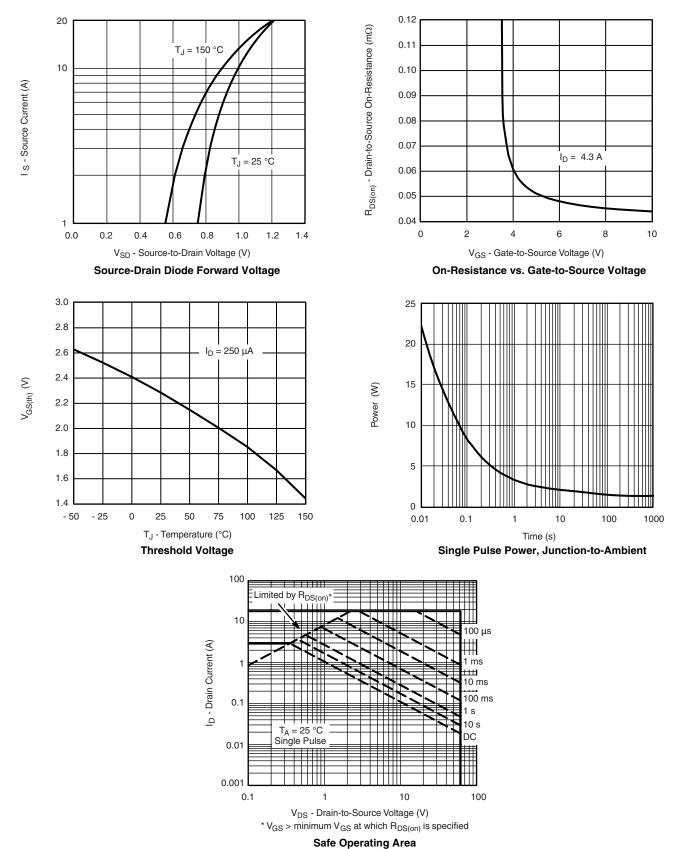
125

150

Si4900DY

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





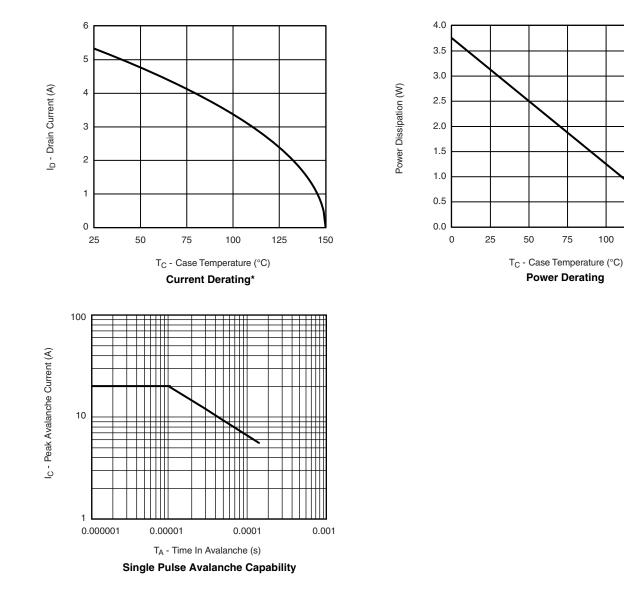
Si4900DY

125

150

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

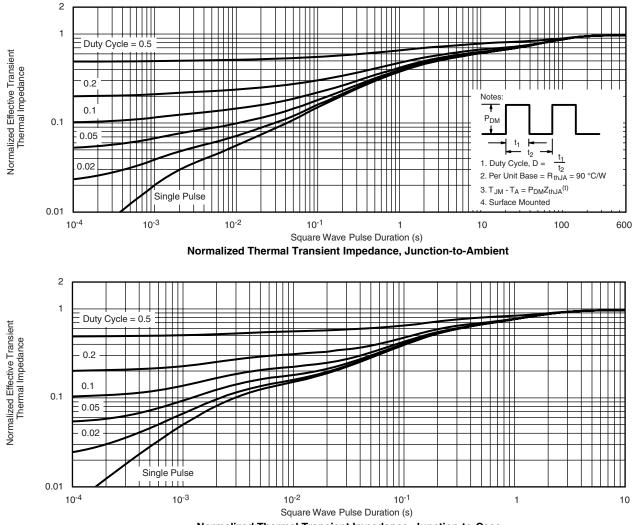


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?73272.



Package Information

Vishay Siliconix

SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					

Application Note 826

Vishay Siliconix



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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